# EE-312L Power Electronics Laboratory Project (CLO3)

Session 2018, 6th Semester June 20, 2021

University of Engineering and Technology Lahore, Pakistan

### 1 Introduction

Multilevel inverters are playing a dominant role in modern smart grids. High power is obtained by using multiple medium power sources at the input of a multilevel inverter. Some of the medium voltage sources are batteries, solar panels or super capacitors etc. Therefore, a multilevel inverter is an inescapable component of modern grid.

The main advantage of using multilevel inverters in modern power systems is to get a nearly approaching sinusoidal output voltage without a load side filter or with a very small size filter as compared to a conventional H-bridge inverter whose filter size is very large. Other advantages of multilevel inverters include low dv/dt stress across the switches, low voltage rating for switches and low switching losses. A typical output voltage waveform of a 7-level inverter is shown in Figure 1.

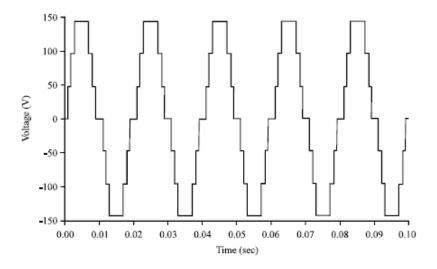


Figure 1: Output voltage waveform of a multilevel inverter (Ref: Nandhini Gayathri et-al)

## 2 Project Description

Consider a single phase cascaded H-bridge multilevel inverter shown in Figure 2. The inverter is being fed by two independent DC voltage sources  $V_1$  and  $V_2$ . The output of first stage is  $v_{H1}$  whereas the output of second stage is  $v_{H2}$ . The total voltage between terminal A and N is  $v_{H1} + v_{H2}$ . The PWM for each MOSFET (Switch) is decided by tracking the path of voltage sources to the output terminals for desired voltage level. A two stage cascaded H-

bridge multilevel inverter shown in Figure 2 can have 5-level, 7-level or 9-level output voltage depending on the magnitude of both voltage sources (keep in mind that those three different output voltage waveforms can be obtained using the same hardware).

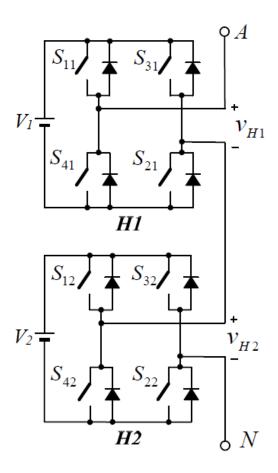


Figure 2: Circuit diagram of a cascaded H-bridge inverter

## Important Note

You are required to simulate the circuit of Figure 2 on MATLAB/Simulink as well as perform its hardware implementation on Printed Circuit Board (PCB). You are free to choose the values of input DC voltage sources as well as the load power rating as long as you remain within the current rating of copper tracks of PCB (1.5mm track width for power side). You are not required to design the PCB as a schematic diagram of the circuit of Figure 2 is provided at the last page of this document whose PCB design (gerber

files) are also available in the zip folder that you can freely use to fabricate the PCB. A suggested way to fabricate the PCB is to use https://jlcpcb.com/ or https://www.pcbway.com/ who can fabricate 10 PCBs for 2-5USD (excluding shipping). Therefore, one order of 10 PCBs is sufficient for 10 groups. You are free to choose other available options to fabricate the PCB.

#### 2.1 Task 1

Based on your chosen values of both input voltage sources and load power, determine the electrical ratings of all the switches and show them in tabular form.

#### 2.2 Task 2

Implement Phase Shifted Carrier Based PWM (PSCPWM) for the 5-level, 7-level and 9-level inverter, obtain the output voltage waveform at each stage and then resultant voltage waveform. Do not forget to include the waveforms of each gate pulse. Perform FFT analysis on the Simulink and determine Total Harmonic Distortion (THD) of the voltage.

#### 2.3 Task 3

Implement Level Shifted Carrier Based PWM (LSCPWM) for the 5-level, 7-level and 9-level inverter, obtain the output voltage waveform at each stage and then resultant voltage waveform. Do not forget to include the waveforms of each gate pulse. Perform FFT analysis on the Simulink and determine Total Harmonic Distortion (THD) of the voltage.

#### 2.4 Task 4

Connect a resistive load and obtain the waveforms of output voltage and output current.

#### 2.5 Task 5

Connect an RL load and obtain the waveforms of output voltage and output current.

## 3 Deliverables

You are required to submit a detailed report (LaTeXbased) and simulation files in a zip folder. Report should include the following contents.

- Title Page
- Abstract (Motivation, What has been done, What has been achieved, etc.)
- Table of Contents
- List of Figures and Tables
- List of Tables
- Introduction (Motivation, Problem Statement and Organization, about one paragraph each, maximum 3 pages, 1 and half page is enough)
- Literature Review (About 3-5 pages with references ranging from basic/classical to latest)
- Software Implementation
- Hardware Implementation
- Results and Discussion
- Conclusions and Future Works (max one page, one paragraph for each point)
- References (IEEE style)
- Appendices (if any)

Please use the FYP template of the department for this report. It should be clear that which simulation belongs to which task/sub-task. Please mention the name and path of the file for each result (figure, table or graph) in the respective caption/title. Failure to follow this instruction will result zero points in that portion of simulations. The zip folder should have two sub-folders named as "Report" (containing pdf file of the report) and "Simulations" (containing the simulations according to the path and name as specified in their corresponding result caption or title). Please import the data into the MATLAB workspace and plot the results with good resolution. Screen shots will not be accepted.

## Submission Deadline

July 30, 2021

# **Project Groups**

You can work on this project in a group with a maximum of four (4) students

## 3-D View of Fabricated PCB

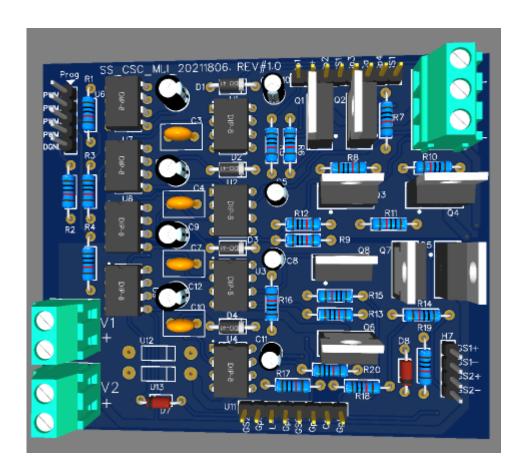


Figure 3: 3-D View of Fabricated PCB

